

Issue	Market Index	VIP Interview	Cover Story	IC Market Forces		Components & Modules	Distribution & Supply Chain		Manufacturing & Testing	Capital Market	Purchasing Watch	Expert Opinion	Specials
				IC Observations	IC Short Supply	Components & Modules	Distribution Strategy	Leadtime and Inventory					
January Booking deadline: Nov. 23	•	•	Prospect of semiconductor application trends in 2021	- Analog IC - DSP	•	Connector	Outlook for the distribution market in 2021	•		•	•	•	
February Booking deadline: Dec. 22	•	•	5G small cell	- FPGA	•	Capacitor	Distributor survey	•	Wafer manufacturing		•	•	
March Booking deadline: Jan. 22	•	•	TWS Bluetooth Headset	- Wi-Fi6	•	MOSFET	Authorized agent	•		•	•	•	
April Booking deadline: Feb. 24	•	•	Smart security	- RISC-V Mcu	•	Fingerprint recognition	Overseas trade	•	Packaging & testing		•	•	
May Booking deadline: Mar. 23	•	•	intelligent instrument market	- Power Manager - Wireless fast charge	•	Wire winding Inductor	Intelligent warehouse Intelligent logistics	•		•	•	•	
June Booking deadline: Apr. 22	•	•	Internal supply chain cycle	- RF chip	•	- Crystal Oscillator - Motor	Small batch distribution	•	IC test		•	•	
July Booking deadline: May 23	•	•	Intelligent charging pile	- MEMS sensor	•	Resistance	Technical distribution	•		•	•	•	
August Booking deadline: June 23	•	•	MCU market analysis	- GPU	•	- 3D Camera - sub-screen camera	Digital supply chain	•	New manufacturing materials		•	•	
September Booking deadline: July 22	•	•	Big data storage	- Display driver IC	•	- LIDAR - mmWave radar	Domestic substitution	•		•	•	•	
October Booking deadline: Aug. 23	•	•	Emerging display technologies(Micro LED/ Mini LED)	- Machine vision - CMOS	•	Speech recognition	Supply chain management	•	PCB manufacturing		•	•	
November Booking deadline: Sept. 19	•	•	Smartphone market analysis	- Wearable/AR VR	•	IGBT	Component e-commerce	•		•	•	•	
December Booking deadline: Oct. 24	•	•	"Lights out" factory/ Automated industry	- CPU	•	Communication module	Inventory management	•	Automated test		•	•	Distributor and Supply Chain Special Issue

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Note: The publisher retains the right to reschedule any topic in the calendar.